ABSTRACT OF THE DISCLOSURE

PACKAGING AND INTERCONNECTION OF CONTACT STRUCTURE

A packaging and interconnection of a contact structure formed of a contact structure made of conductive material and formed on a contact substrate through a micro-fabrication process, a contact pad connected to contact substrate and provided at the bottom surface of the contact substrate, a printed circuit board (PCB) pad provided on a printed circuit board (PCB) substrate to be electrically connected with the contact pad, a conductive member for connecting the contact pad the PCB pad, an elastomer provided under the contact substrate for allowing flexibility in the interconnection and packaging of the contact structure, and a support structure provided between the elastomer and the PCB substrate for supporting the contact structure, contact substrate and elastomer.

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